

Product Change Notification

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Product Change Notification Number: GC203761

Date: 10-SEPTEMBER-2020

Title: New flux and underfill materials for the TSPC603R, PC745/755 and PC107 products in HiTCE CBGA package.

Product Identification:

All Teledyne product of PC745/755/107/603R series with mainly 'GH' package code.
 See list in **ANNEX** on page 2.

Reason for Change:

- | | | |
|--|---|---|
| <input type="checkbox"/> Design | <input type="checkbox"/> wafer Processing | <input type="checkbox"/> wafer Materials |
| <input type="checkbox"/> Logistics | <input type="checkbox"/> Other | <input type="checkbox"/> Manufacturing Location |
| <input checked="" type="checkbox"/> Process Material | <input checked="" type="checkbox"/> Assembly Material | <input type="checkbox"/> Quality/Reliability |
| | <input type="checkbox"/> Product Marking | |

Change Description:

In accordance with Teledyne-e2v policy regarding compliance with European REACH regulation, the flux material used for the assembly of the products listed below is changed. This modification is associated with a change of the underfill for material compatibility.

Anticipated Impact of Product Change (Form, Fit, Function):

Except a slight darkening of the underfill around the die, the change will not impact the form, fit, or function of the products.

Products datasheets and package specifications remain the same.

Identification Method to Distinguish Change:

An earliest datecode of implementation can be identified and shared upon request as reference information related to this change. This earliest datecode of implementation may vary per product and depends on the depletion of existing inventory.

Upon implementation, Teledyne e2v may continue to ship pre-change material until inventory is depleted.

Qualification Data:

- available will be available in June-2021 not applicable

Samples:

- prototypes available will be available not applicable

Quantifiable Impact on Quality & Reliability: *None expected.*

Implementation Date*: Estimated end in June-2021

**The Estimated Implementation Date is the forecasted date that a customer may expect to receive changed product. This is determined by the estimated date of inventory depletion on the PCN issue date. This may be affected by fluctuations in supply and demand. Consequently, although customers should be prepared to receive changed product on this date, Teledyne e2v semiconductors will continue to ship pre-changed product until a time in which inventory has been depleted. This may result in pre-changed product being shipped to customers after this forecasted date.*

Teledyne e2v semiconductors contact:

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Please contact your local Teledyne-e2v sales representative for any commercial inquiry.

APPROVAL by TRB

Teledyne e2v semiconductors will deem this change accepted unless specific conditions of acceptance are provided in writing within 30 days from the date of this notice. All correspondence must be sent to the contact e-mail addresses indicated above.

A Teledyne e2v semiconductor assumes no responsibility for any errors that may appear in this document.

The supply of products will be subject to Teledyne e2v general terms and conditions of sale or any specific contractual terms agreed between the parties.

If you would like to see already available announcements or receive customer notifications by email, please subscribe to our customer notification mailing list via: <https://www.teledyne-e2v.com/products/semiconductors/obsolescence-planning-slim/>

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ANNEX - List of product of interest

- Below detailed list of active Part Numbers impacted by this change.
- All non RoHS (lead) parts (code GH) in HiTCE CBGA package Assembly are affected by this change. For RoHS version future availability, please consult us.

PC745BMGH350LBEPL2	PC107AVGH100LD
PC745BMGH350LE	PC107AEGH100LD
PC745BVGH300LE	PC107AMGH100LC
PC745BVGH350LE	PC107AVGH100LC
PC755BEGH300LE	
PC755BMGH300LE	
PC755BMGH300LEZF7	PC603RVGH8LCBEPK1
PC755BMGH350LE	TSPC603RVGH12LC
PC755BMGH366LE	TSPC603RVGH10LC
PC755BMGU300LE	TSPC603RMGH8LC
PC755BVGH300LBEPR2	TSPC603RVGH8LC
PC755BVGH300LE	TSPC603RMGH12LC
PC755BVGH350LE	
PC755CVGH400LE	